

## SOLDERING CONDITIONS 焊接條件

□ For Chip Type Conductive Polymer Aluminum Solid Electrolytic Capacitors & Chip Type Conductive Polymer Hybrid Aluminum Electrolytic Capacitors 適用於貼片式導電性高分子固態鋁電解電容器及貼片式導電性高分子混合型鋁電解電容器

### Recommended Conditions for Reflow Soldering 推薦回流焊條件

#### ● Conductive Polymer Aluminum Solid Electrolytic Capacitors 貼片式導電性高分子固態鋁電解電容器

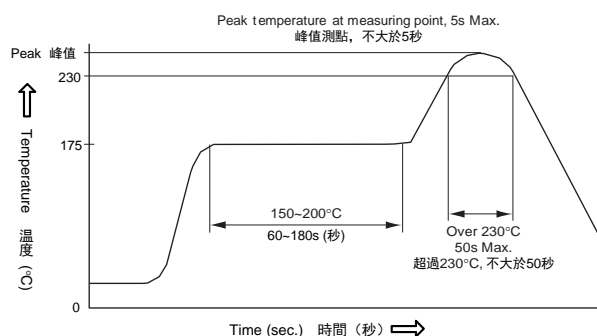
- (1) Preheating shall be done at +150°C to 200°C and for 60 to 180 seconds.  
預熱應在+150°C~200°C 及 60~180 秒內完成。
- (2) The duration for over +230°C temperature at capacitor surface shall not exceed 60 seconds.  
電容器表面溫度超過+230°C 的持續時間不得超過 60 秒。
- (3) The standard temperature profile differs by every reflow method.  
溫度曲線圖的溫度標準會因回流焊方式的不同而不同。
- (4) Peak temperature +260°C or below: Reflow shall be done 1 cycle only.  
峰值溫度在+260°C 或以下：回流焊次數只能是 1 次。
- (5) Peak temperature +250°C or below: Reflow shall be done within 2 cycles.  
峰值溫度在+250°C 或以下：回流焊次數最多是 2 次。
- (6) Please make sure that the parts have enough cooling time between the first and second soldering process.  
請確保在第 1 次和第 2 次之間的產品有足夠的冷卻時間。
- (7) The temperature at capacitor top shall not exceed the peak temperature.  
電容器表面的溫度不得超過峰值溫度。
- (8) Please contact us if your condition is over the maximum.  
如使用條件超出最大值，請與我們聯繫。

#### ● Conductive Polymer Hybrid Aluminum Electrolytic Capacitors 貼片式導電性高分子混合型鋁電解電容器

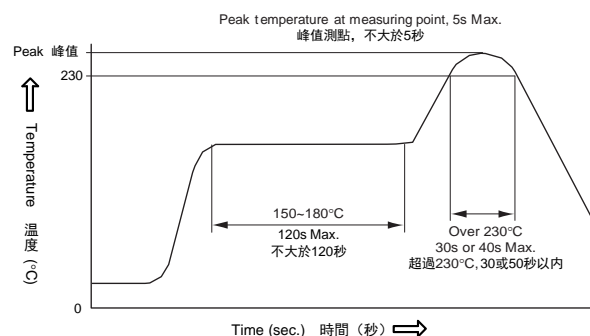
- (1) Preheating shall be done at +150°C to 180°C and for 120 seconds.  
預熱應在+150°C~180°C 及 120 秒內完成。
- (2) Peak temperature +260°C or below: Reflow shall be done 1 cycle only.  
峰值溫度在+260°C 或以下：回流焊次數只能是 1 次。
- (3) Peak temperature +250°C or below: Reflow shall be done within 2 cycles.  
峰值溫度在+250°C 或以下：回流焊次數最多是 2 次。
- (4) Please make sure that the parts have enough cooling time between the first and second soldering process.  
請確保在第 1 次和第 2 次之間的產品有足夠的冷卻時間。
- (5) Please contact us if your condition is over the maximum.  
如使用條件超出最大值，請與我們聯繫。

### Classification Reflow Profile 回流焊曲線圖

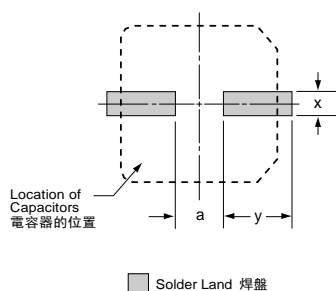
#### ● Conductive Polymer Aluminum Solid Electrolytic Capacitors 貼片式導電性高分子固態鋁電解電容器



#### ● Conductive Polymer Hybrid Aluminum Electrolytic Capacitors 貼片式導電性高分子混合型鋁電解電容器



### Recommended Solder Land Size on PC Board 推薦安裝尺寸 (Unit: mm)



Size 尺寸	a	y	x
Ø4	1.0	2.6	1.6
Ø5	1.4	3.0	1.6
Ø6.3	2.1	3.5	1.6
Ø8 × 6.7~9	2.1	4.0	1.6
Ø8 × 10~12	3.0	3.5	2.5
Ø10	4.0	4.0	2.5

**Note:** All design and specifications are for reference only and is subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.

注：以上所提供的設計及特性參數僅供參考，任何修改不作預先通知。如果在使用上有疑問，請在採購前與我們聯繫，以便提供技術上的協助。

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